



# **E104-BT30 User Manual**

**CSRA64215 Wireless Audio Module**



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# 1. Overview

## 1.1 Brief introduction

E104-BT30 is a multifunctional and cost-effective module developed by our company for audio Bluetooth transmission. The main control uses the CSRA64215 chip of CSR to provide the module with high-quality sound and compatibility. The Bluetooth module uses a driver-free method. Users only need to connect the module to the application product to quickly achieve high-quality Bluetooth audio transmission and enjoy wireless music. And the module supports APTX, APTXLL, ACC and other high-quality sound effects.



## 1.2 Features

- Bluetooth V4.2+EDR standard specifications
- Support TWS
- Automatic reconnection
- MIC input
- APTX、ACC、Aptx Low latency
- AVRCP 1.5、A2DP 1.3 、HFP 1.5
- CSR latest sixth-generation CVC enhancement technology implements noise reduction and echo cancellation
- PCB antenna, the maximum communication distance is 50 meters in open air
- Battery level display

## 1.3 Application

- High-quality wireless stereo headphones;
- High-fidelity speaker and sound;
- Bluetooth car audio&video;
- Bluetooth speaker calling.

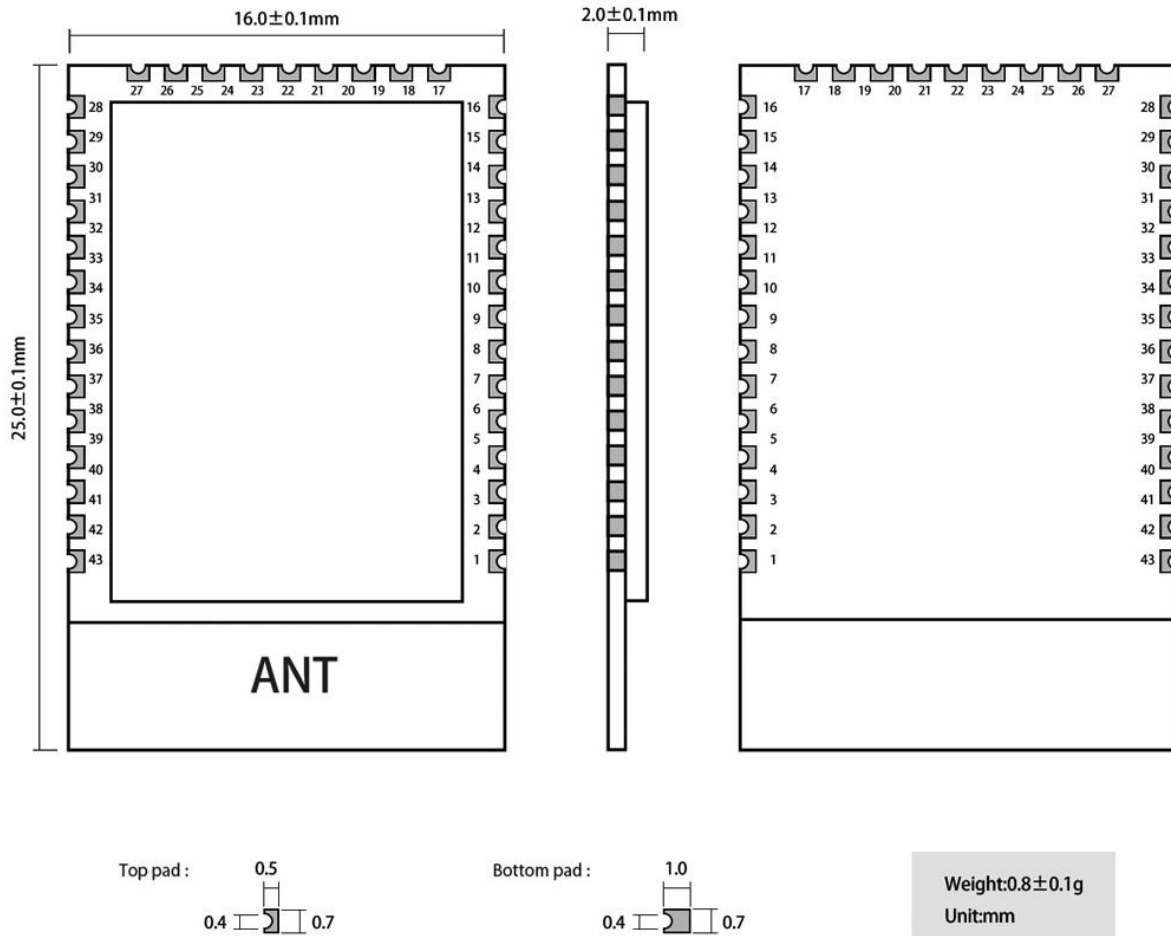
# 2. Specification and parameter

## 2.1 Electrical performance parameters

| Main parameter              |                                  | Performance |       |       | Remark   |
|-----------------------------|----------------------------------|-------------|-------|-------|--|
|                             |                                  | Min.        | Typ.  | Max.  |  |
| Operating voltage (V)       |                                  | 1.9         | 3.3   | 3.6   | ≥3.3V can guarantee output power                             |
| Communication level (V)     |                                  | 1.8         | 3.3   | 3.6   | Level is determined by VDD-PADS-1 level and VDD-PADS-2 level |
| Operating temperature (°C)  |                                  | -40         | 20    | +85   | Industrial design  |
| Operating frequency (MHz)   |                                  | 2402        | -     | 2480  | Support Bluetooth protocol standard frequency band           |
| Power consumption           | Not connected current (mA)       | 0.5         | -     | 8     | Bluetooth is discoverable                                    |
|                             | Connected unplayed current (mA)  | 10          | -     | 14    | Bluetooth is connected but no music is playing               |
|                             | Audio output status current (mA) | 15          | -     | 18    | Bluetooth is connected and playing music                     |
| Max Tx power (dBm)          |                                  | -           | 9     | 9     | --   |
| Receiving sensitivity (dBm) |                                  | -           | -90.5 | -92.0 | BDR  |

| Main parameter         | Description | Remark   |
|------------------------|-------------|--|
| Distance for reference | 50m         | Clear and open area, antenna height: 2.5m, indoor communication ≥10m |
| Crystal frequency      | 26MHz       | --   |
| On-board Flash         | 4M          | --   |
| Package                | SMD         | --   |
| Connector              | 1.1mm       | Refer to size drawings and PCB package library for details           |
| Size                   | 16*25mm     | Refer to size drawings for details                                   |
| Antenna                | PCB         | 50 ohm impedance   |

## 2.2 Size and pin definition



| Pin No. | Pin item | Pin direction | Application   |
|---------|----------|---------------|---|
| 1       | GND      | P             | Ground, connect to power reference ground                   |
| 2       | AIO0     | I/O           | Analog programmable I/O pin 0 (reserved function)           |
| 3       | PIO4     | I/O           | SPI-CS debug load pin                                       |
| 4       | PIO16    | I/O           | Module audio output indication pin, high level is effective |
| 5       | PIO3     | I/O           | SPI-MISO debug load pin                                     |
| 6       | SPI-PCM  | I             | SPI / PCM input selection, 0 = PCM / PIO interface, 1 = SPI |
| 7       | PIO2     | I/O           | SPI-MOSI debug load pin                                     |
| 8       | PIO17    | I/O           | AUX input trigger pin (reserved function)                   |
| 9       | PIO5     | I/O           | SPI-CLK debug load pin                                      |
| 10      | RST      | I             | Module reset pin, pull down for 5ms to trigger reset        |
| 11      | LED1     | O             | Bluetooth status indication LED1 driver output              |
| 12      | LED0     | O             | Bluetooth status indication LED0 driver output              |
| 13      | LED2     | O             | Bluetooth status indication LED2 driver output              |

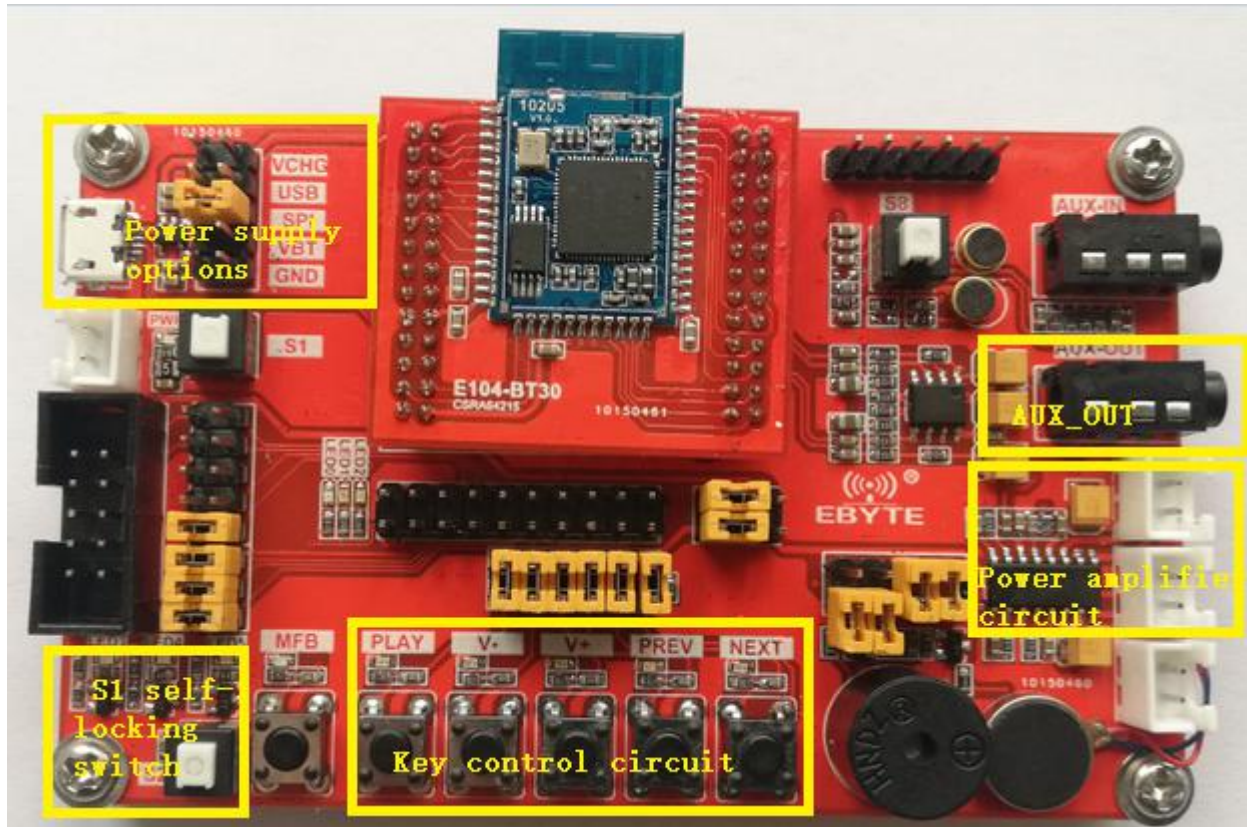
|    |                |     |  |
|----|----------------|-----|--|
| 14 | 1V35-SMPS      | P   | Module 1.35V power output, external decoupling capacitor is recommended, see Recommended circuit for details                                 |
| 15 | VREGENA<br>BLE | I   | Bluetooth module power-on / power-off control pin, high level is effective. Note that the module needs to be initialized before powering on. |
| 16 | VCHG           | P   | Internal charger input, usually connected to VBUS, see Typical application circuit for details   |
| 17 | CHG_EXT        | P   | External battery charger control (reserved function)   |
| 18 | VBAT_SE        | P   | Battery charge sensing input (reserved function)   |
| 19 | VBAT-IN        | P   | Battery power input pin, cannot exceed 3.6V, otherwise the module will be damaged  |
| 20 | GND            | P   | Ground, connect to power reference ground  |
| 21 | USB-DN         | I/O | USB cable negative (reserved function)   |
| 22 | USB-DP         | I/O | USB cable positive (reserved function)   |
| 23 | PIO18          | I/O | General-purpose I / O (reserved function)  |
| 24 | PIO21          | I/O | General-purpose I / O (reserved function)  |
| 25 | PIO6           | I/O | General-purpose I / O (reserved function)  |
| 26 | PIO1           | I/O | Next song Key input, high level is effective   |
| 27 | PIO8           | I/O | Previous song Key input, high level is effective   |
| 28 | VDD-PADS<br>-1 | P   | Input and output port power supply 1, usually 1.8V power supply connection   |
| 29 | 1V8-SMPS       | P   | Module 1.8V power output, external decoupling capacitor is recommended, see 4.2 Recommended circuit for details                              |
| 30 | VDD-PADS<br>-2 | P   | Input and output port power 2, usually 1.8V power connection   |
| 31 | PIO7           | I/O | Volume + Key input, high level effective, long press to continuously increase;   |
| 32 | PIO9           | I/O | Play / Pause Key input, high level effective   |
| 33 | PIO0           | I/O | Volume - Key input, high level effective, long press to continuously decrease;   |
| 34 | MIC-AN         | I   | Channel A line or microphone input negative  |
| 35 | MIC-AP         | I   | Channel A line or microphone input positive  |
| 36 | MIC-BIAS       | I   | Microphone bias  |
| 37 | LINE-BN        | I   | Channel B line input negative  |
| 38 | LINE-BP        | I   | Channel B line input positive  |
| 39 | SPK-RN         | O   | Right channel speaker output negative  |
| 40 | SPK-RP         | O   | Right channel speaker output positive  |
| 41 | SPK-LN         | O   | Left channel speaker output negative   |
| 42 | SPK-LP         | O   | Left channel speaker output positive   |
| 43 | GND            | P   | Ground, connect to power reference ground  |

pay attention:

The function description of the above pins is only for the default program functions of our company. If you need other functions, please contact us for customization. For the self-developed pin functions, please refer to the official user manual of CSRA64215.

### 3. Quick start

This quick use requires our test baseboard.



#### Instruction

##### Power supply options:

The jumper cap on this circuit is used to select the power supply mode, which is selected according to the user's power supply mode.

##### Boot:

Press the S1 self-locking switch, and then LED0 (green) blinks. 2 seconds later, LED0 and LED2 (blue) blink alternately. At this time, the Bluetooth named E104-BT30 V1.0 can be searched on the phone, and you can connect

##### AUX\_OUT output power:

Connect the 3.5mm headphones here

##### Power amplifier circuit:

If the user has a 3W speaker, you can directly connect the two terminals of the power amplifier circuit.

##### Key control circuit:

PLAY: Music play and pause button, it has the following states.

When connect to a mobile phone, short press the PLAY button to play music and pause.

When connect to a mobile phone, long press to disconnect the current connection and enter the discoverable state.

At this time, LED1 (red) will blink once.

When connect to a mobile phone, when there is an incoming call, short press the PLAY button to answer the call.

V-: This button is volume reduction. There are long-press and short-press of the button. Long-press can continuously decrease the volume. Short-press decreases



it a little.

V +: This button is volume increase. There are long-press and short-press of the button. Long-press continuously increases the volume, and short-press increases it a bit.

Note: The above two volume buttons cannot synchronize the volume of the mobile phone by default. If you need to synchronize the volume of the mobile phone, you need to turn on the "volume synchronization control" in the developer mode of the mobile phone. After it is turned on, please clear the phone pairing and then connect again.

PREV: This button is the previous song button, which can control the phone to play the previous music

NEXT: This button is the next song button, which can control the phone to play the next music,

H: On/Off circuit

If it is currently turned off, press it again to turn it on. If it is turned on, press it again and then turn it off.

Power on, MFB indicator (green) is always on.

Power off, MFB indicator (green) goes out.

TWS function use:

Requires two modules.

TWS refers to the multi-connection mode, which is also called "pair-to-box". Two speakers can be configured as the master and slave. The master enters the initiating connection mode, and the slave enters the waiting connection mode.

Enter TWS host: PLAY button + PREV button, the blue light flashes quickly after pressing both buttons simultaneously for 2 seconds

Enter slave mode: PLAY button + NEXT button, the blue light flashes quickly after pressing both buttons simultaneously for 2 seconds

When there is a master and a slave, wait for the two sides to connect (about 10s). After the host long presses the PALY button, the phone can connect to the host and use TWS normally.

End TWS connected: Press PREV and NEXT simultaneously for about two seconds to end TWS connected mode.

## 4. Hardware circuit design and requirements

### 4.1 Hard design

- VREGENABLE (MFB) cannot directly pull up the resistor to VBAT, VREGENABLE (MFB) controls the turning on and off of the Bluetooth chip. You must wait until the chip is powered on to complete the initialization before you can start the turn it on, and cannot delay via resistors and capacitors(unstable). Related delay circuit can refer to the recommended circuit in the official user manual.
- The audio output and MIC input of the module are both differential circuits. For related hardware design, please refer to our hardware design circuit.
- The module is a PCB antenna. Do not route or copper under the antenna during layout and wiring. Hollowing is recommended.
- High-frequency digital routing, high-frequency analog routing, and power routing must be avoided under the module. If it is necessary to pass through the module, assume that the module is soldered to the Top Layer, and the copper is spread on the Top Layer of the module contact part(well grounded), it must be close to the digital part of



the module and routed in the Bottom Layer ;

- Assuming the module is soldered or placed over the Top Layer, it is wrong to randomly route over the Bottom Layer or other layers, which will affect the module's spurs and receiving sensitivity to varying degrees ;
- It is recommended to use a USB or battery to power the module. The ripple factor of the power supply should be as small as possible, and the module should be reliably grounded;
- Please pay attention to the correction of the positive and negative of the power supply, reverse connection may cause permanent damage to the module;
- Please check the power supply to ensure that it is between the recommended power supply voltage, if the maximum value is exceeded, the module will be permanently damaged;
- When designing current supply circuit, 30% margin is recommended to be remained so as to ensure long-term stable operation of the whole module;
- The module should be as far away as possible from the power supply, transformers, high-frequency wiring and other parts with large electromagnetic interference;
- It is assumed that there are devices with large electromagnetic interference around the module that will greatly affect the performance. It is recommended to keep them away from the module according to the strength of the interference. If necessary, appropriate isolation and shielding can be done;
- Assume that there are traces with large electromagnetic interference (high-frequency digital, high-frequency analog, power traces) around the module that will greatly affect the performance of the module. It is recommended to stay away from the module according to the strength of the interference. If necessary, appropriate isolation and shielding can be done;
- The module must not be installed inside metal shield, which will greatly reduce the transmission distance.

## 4.2 Recommended application circuit

Refer to "Recommended Circuit.pdf" for recommended circuit.

## 5. FAQ

### 5.1 Communication range is too short

- The communication distance will be affected when obstacle exists.
- Data lose rate will be affected by temperature, humidity and co-channel interference.
- The ground will absorb and reflect wireless radio wave, so the performance will be poor when testing near ground.
- Seawater has great ability in absorbing wireless radio wave, so performance will be poor when testing near the sea.
- The signal will be affected when the antenna is near metal object or put in a metal case.
- When the power supply at room temperature is lower than the recommended low voltage, the lower the voltage is, the lower the transmit power is.

### 5.2 Module is easy to damage

- Please check the power supply and ensure it is within the recommended range. Voltage higher than the peak will

lead to a permanent damage to the module.

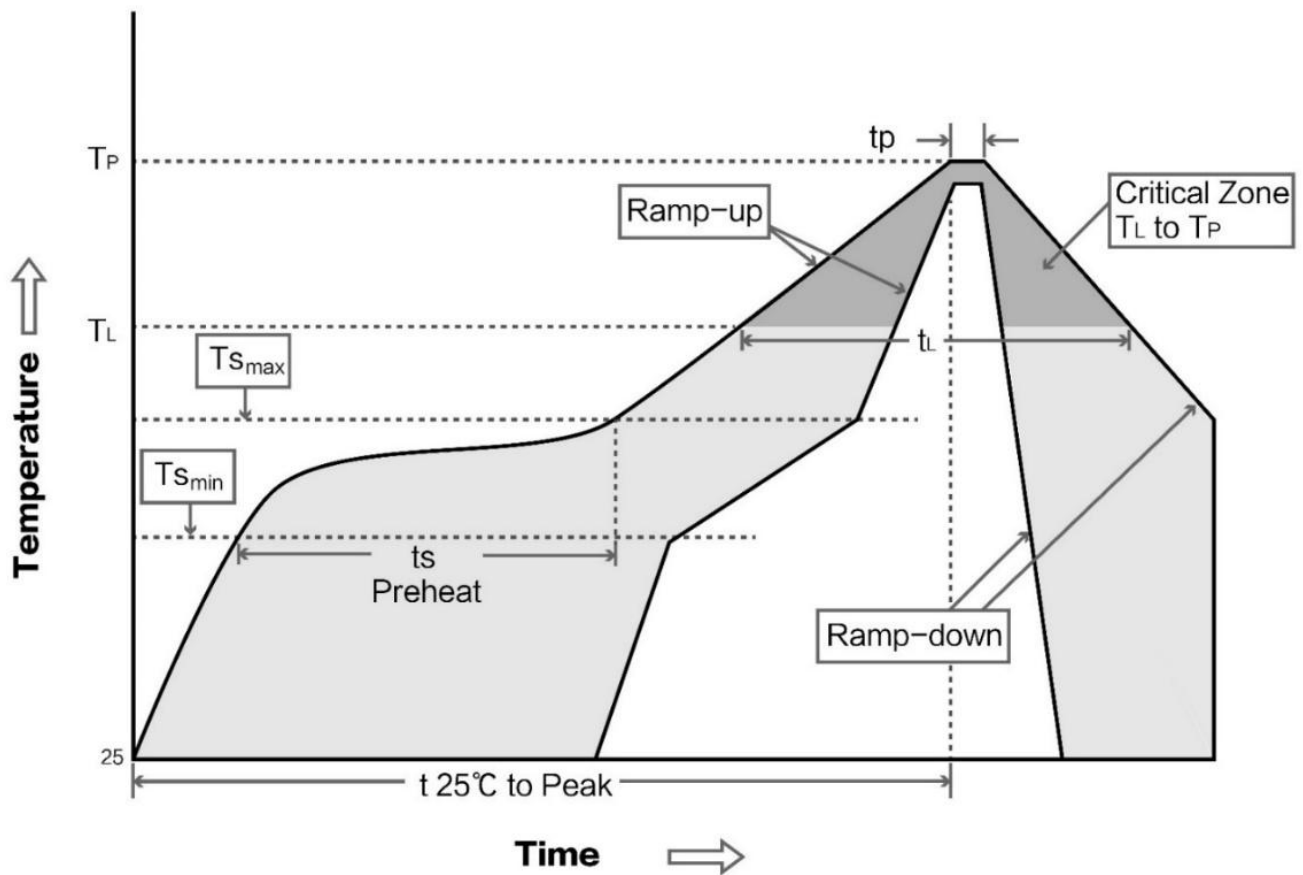
- Please check the stability of power supply and ensure the voltage not to fluctuate too much.
- Please make sure anti-static measures are taken when installing and using, high frequency devices have electrostatic susceptibility.
- Please ensure the humidity is within limited range for some parts are sensitive to humidity.
- Please avoid using modules under too high or too low temperature.

## 6. Welding guidance

### 6.1 Reflow Soldering Temperature

| Profile Feature   | Curve feature                      | Sn-Pb Assembly | Pb-Free Assembly |
|---|------------------------------------|----------------|------------------|
| Solder Paste  | Solder paste                       | Sn63/Pb37      | Sn96.5/Ag3/Cu0.5 |
| Preheat Temperature min (T <sub>smin</sub> )                  | Minimum preheating temperature     | 100℃           | 150℃             |
| Preheat temperature max (T <sub>smax</sub> )                  | Maximum preheating temperature     | 150℃           | 200℃             |
| Preheat Time (T <sub>smin</sub> to T <sub>smax</sub> )(ts)    | Preheating time                    | 60-120 sec     | 60-120 sec       |
| Average ramp-up rate(T <sub>smax</sub> to T <sub>p</sub> )    | Average rising rate                | 3℃/second max  | 3℃/second max    |
| Liquidous Temperature (TL)                                    | Liquid phase temperature           | 183℃           | 217℃             |
| Time (t <sub>L</sub> ) Maintained Above (TL)                  | Time above liquidus                | 60-90 sec      | 30-90 sec        |
| Peak temperature (T <sub>p</sub> )                            | Peak temperature                   | 220-235℃       | 230-250℃         |
| Average ramp-down rate (T <sub>p</sub> to T <sub>smax</sub> ) | Average descent rate               | 6℃/second max  | 6℃/second max    |
| Time 25℃ to peak temperature                                  | Time of 25 ° C to peak temperature | 6 minutes max  | 8 minutes max    |

## 6.2 Reflow Soldering Curve



## 7. E104-BT30

| Model No.                      | Chip      | Frequency    | Distance | Size      | Package | Interface    |
|--------------------------------|-----------|--------------|----------|-----------|---------|--------------|
|                                |           | Hz           | m        | mm        |         |              |
| <a href="#">E104-BT30-V1.0</a> | CSRA64215 | 2.402-2.485G | 50       | 25*16*2.0 | SMD     | Stereo (R\L) |

## 8. Disclaimer

- This manual is as comprehensive and detailed as possible based on the existing materials. Our company reserves the right to modify the manual without further notice.
- This manual is only used as guide. All information in this manual does not constitute any expressed or implied warranty.

## 9. Revision history

| Version | Date       | Description       | Issued by |
|---------|------------|-------------------|-----------|
| 1.0     | 2019-10-22 | Initial version   | -         |
| 1.1     | 2019-10-29 | Format adjustment | Ren       |
| 1.2     | 2020-03-23 |                   | Ren       |

## 10. About us

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